Abstract

Provided is a method for releasing a substrate adsorbed to a first surface of an elastic film included in a substrate holding apparatus of a substrate polishing apparatus,

a plurality of concentric pressure chambers being formed between a top ring body included in the substrate holding apparatus and a second surface of the elastic film, the method including:

a first step of supplying fixed-amount gas to two or more pressure chambers among the plurality of pressure chambers to pressurize the elastic film; and

a second step of sequentially depressurizing the plurality of pressure chambers from outer pressure chambers.

Figure 13